

FEATURES AND SPECIFICATIONS

Features and Benefits

- Sizes 10 to 60 circuits
- Selective Gold- and Tin-plated versions

Reference Information

Packaging: Tray
 UL File No.: E29179-E
 Mates With: 5320-NA and 5320-NB
 Designed In: Millimeters

Electrical

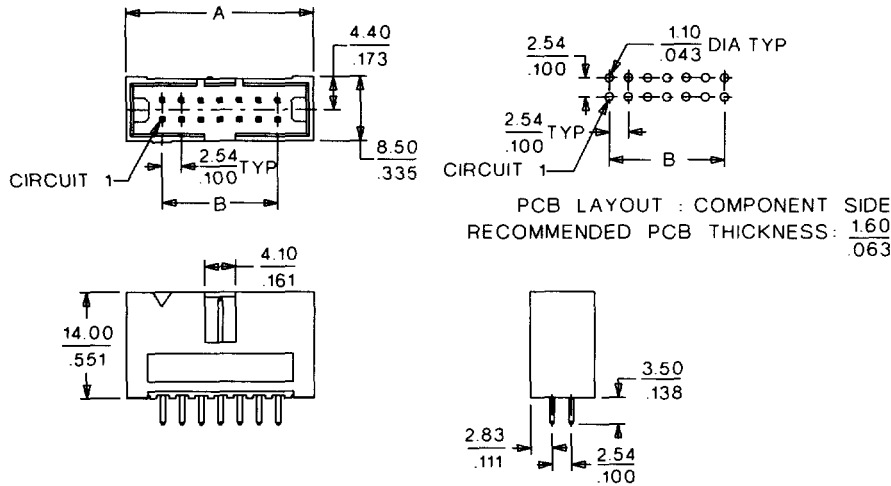
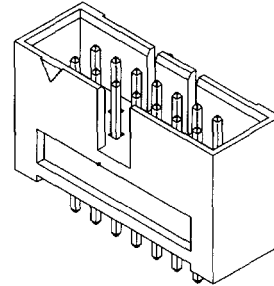
Current: 1.0A
 Contact Resistance: 20mΩ max.
 Dielectric Withstanding Voltage: 500V AC
 Insulation Resistance: 1000 MΩ min.

Physical

Housing: Black glass-filled polyester, UL 94V-0
 Contact: Brass
 Contact Pin: 0.635mm (.025") square
 Plating: See Table
 Temperature: -40 to +105°C

molex® 2.54mm (.100") Pitch
QF 50™
Shrouded Header

5332
Vertical, Dual Row
Single Polarization



ORDERING INFORMATION AND DIMENSIONS

Circuits	Order No.		Dimension	
	Plating NG51	Plating NT2	A	B
10	39-26-7105	39-28-5101	19.66 (.774)	10.16 (.400)
14	39-26-7145	39-28-5141	24.74 (.974)	15.24 (.600)
16	39-26-7165	39-28-5161	27.28 (1.074)	17.78 (.700)
20	39-26-7205	39-28-5201	32.36 (1.274)	22.86 (.900)
26	39-26-7265	39-28-5261	39.98 (1.574)	30.48 (1.200)
30	39-26-7305	39-28-5301	45.06 (1.774)	35.56 (1.400)
34	39-26-7345	39-28-5341	50.14 (1.974)	40.64 (1.600)
40	39-26-7405	39-28-5401	57.76 (2.274)	48.26 (1.900)
50	39-26-7505	39-28-5501	70.46 (2.774)	60.96 (2.400)
60	39-26-7605	39-28-5601	83.16 (3.274)	73.66 (2.900)

Plating NG51: 39μ" (1μm) min. Nickel underplate. Contact area: 4μ" (0.1μm) min. Gold.
 Solder area: 3μm min. Tin/Lead.

Plating NT2: 35μ" (0.9μm) min. Tin overall